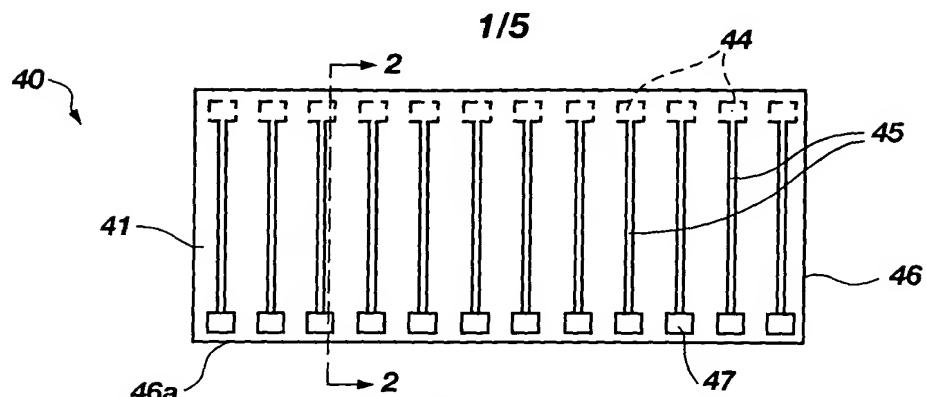


**TITLE: METHODS FOR DESIGNING BOND PAD REROUTING ELEMENTS FOR USE IN STACKED SEMICONDUCTOR DEVICE ASSEMBLIES AND FOR ASSEMBLING SEMICONDUCTOR DEVICES**

Inventor: Corisis et. Al.  
Docket No.: 2269-4814.1US



*Fig. 1*

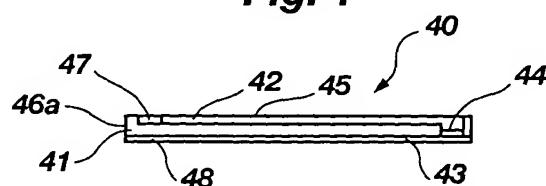
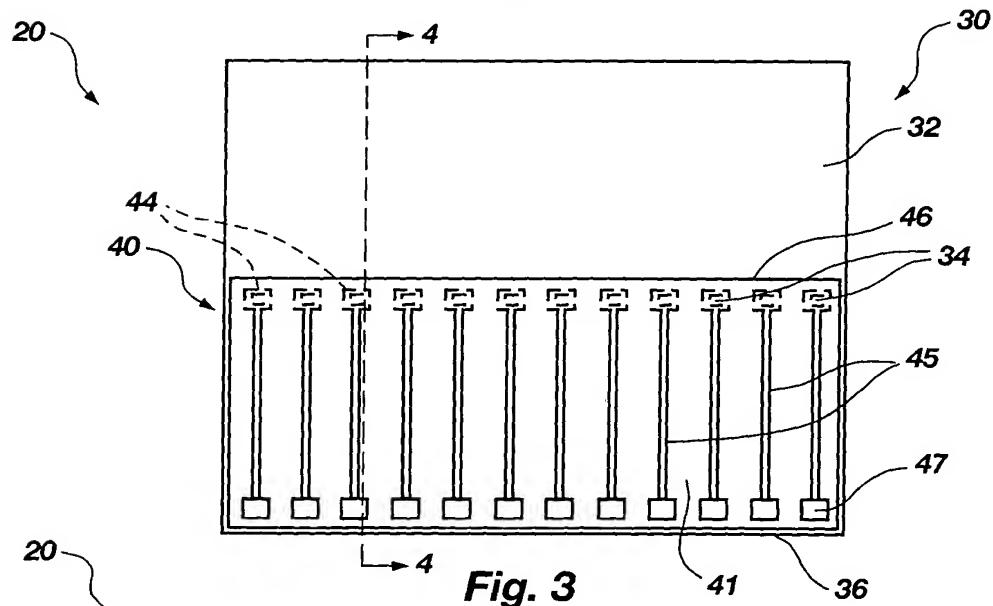
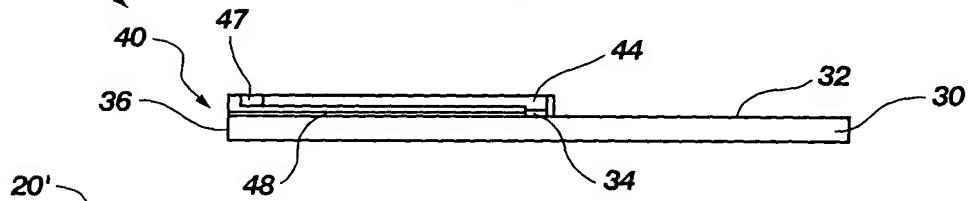


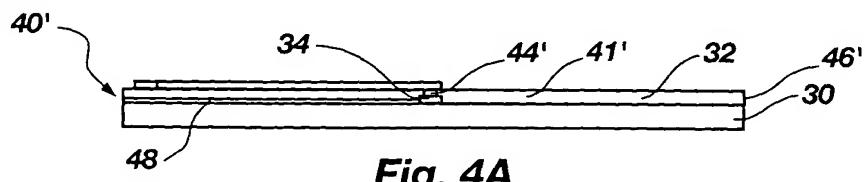
Fig. 2



*Fig. 3*



*Fig. 4*



*Fig. 4A*

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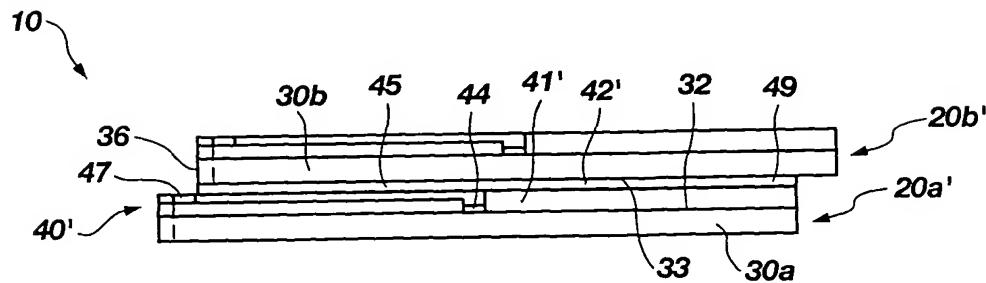


Fig. 5

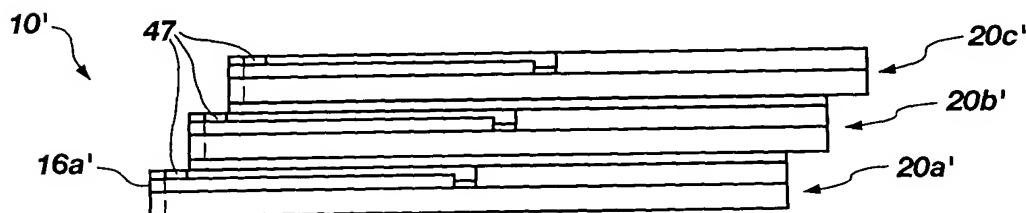


Fig. 6

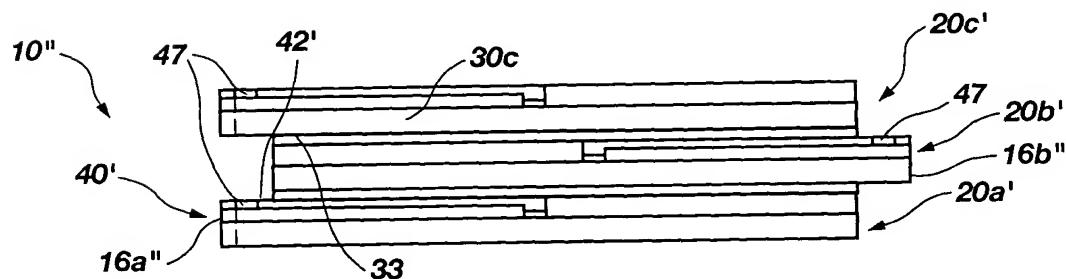


Fig. 7

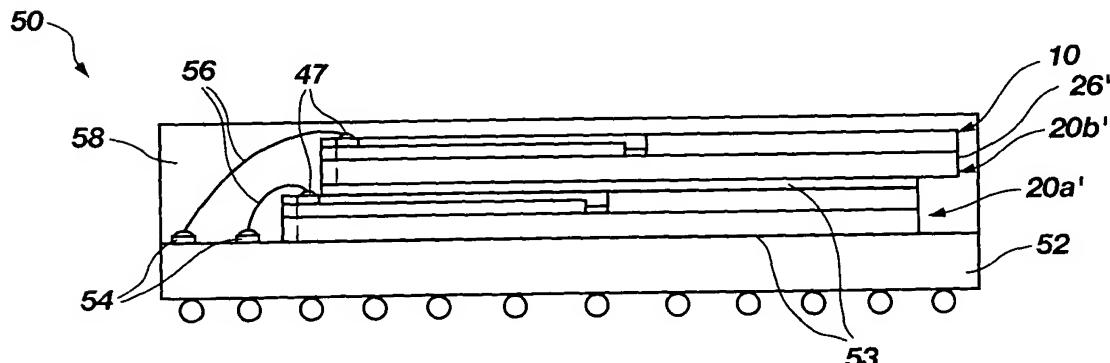
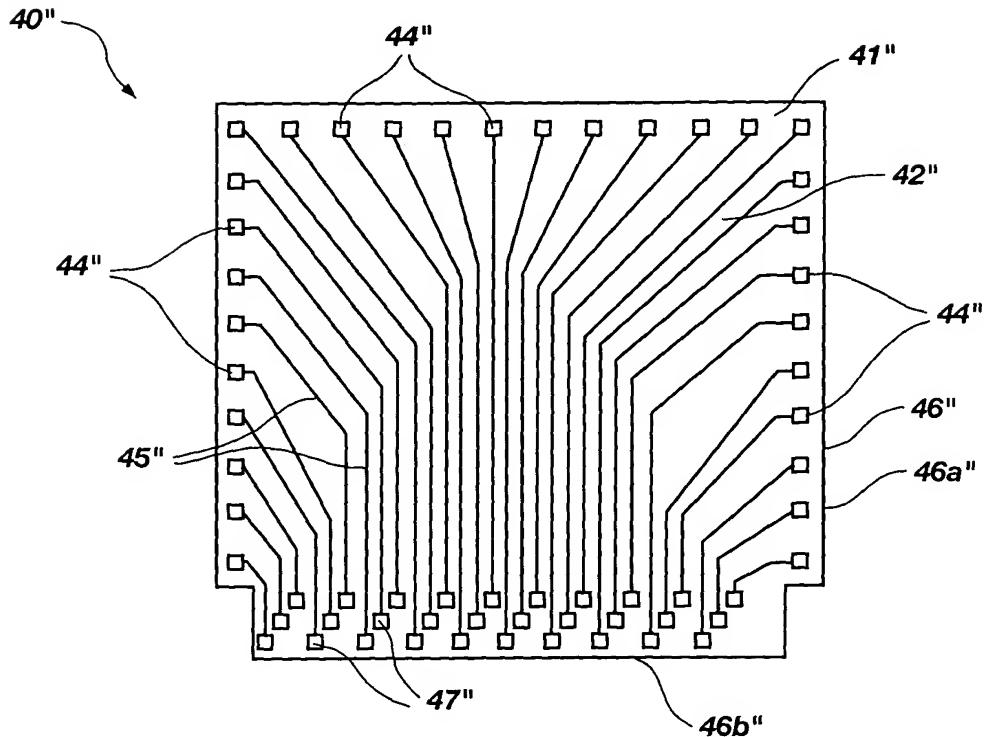
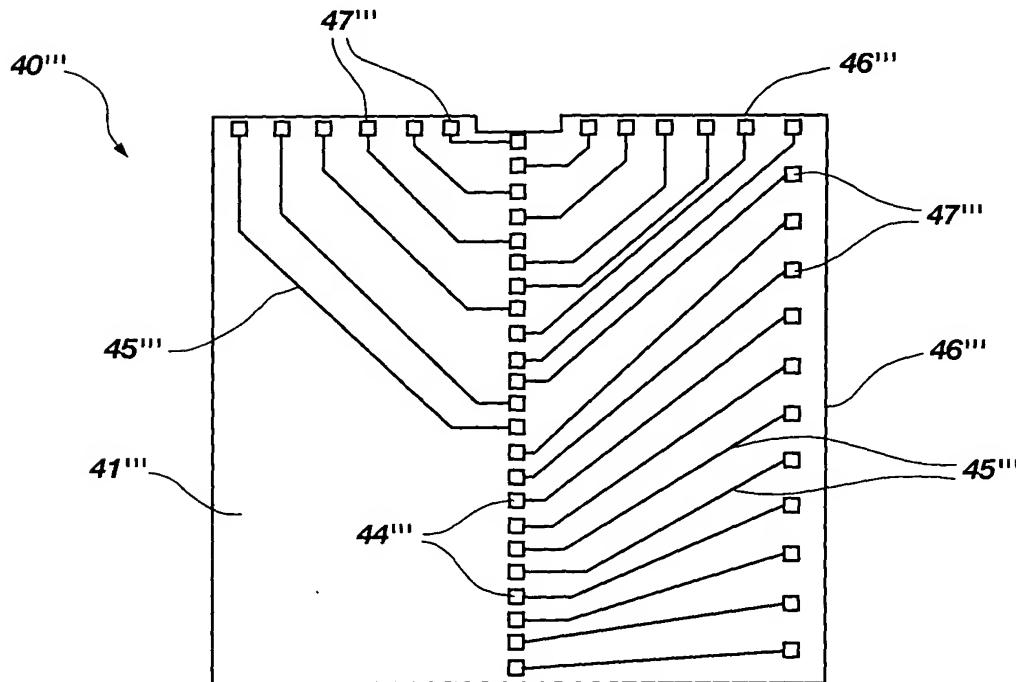


Fig. 8

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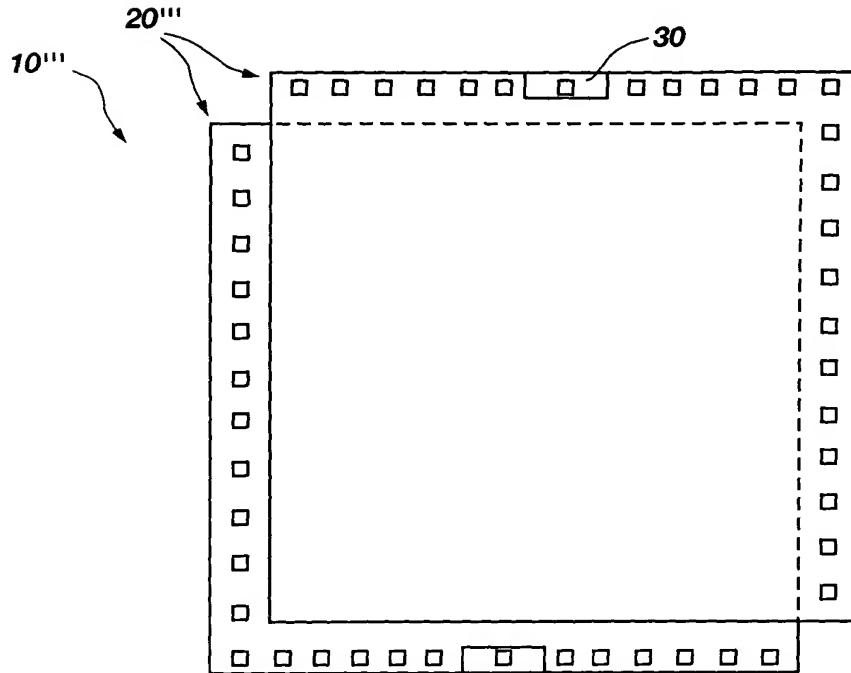


*Fig. 9*

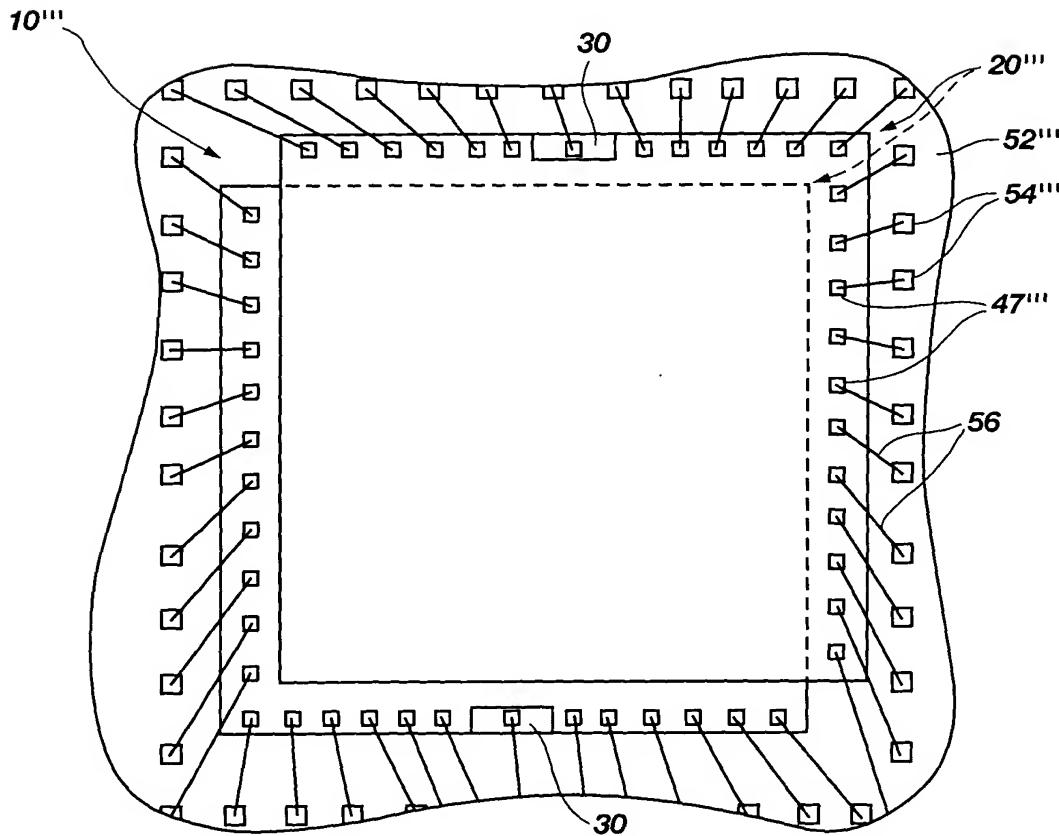


*Fig. 10*

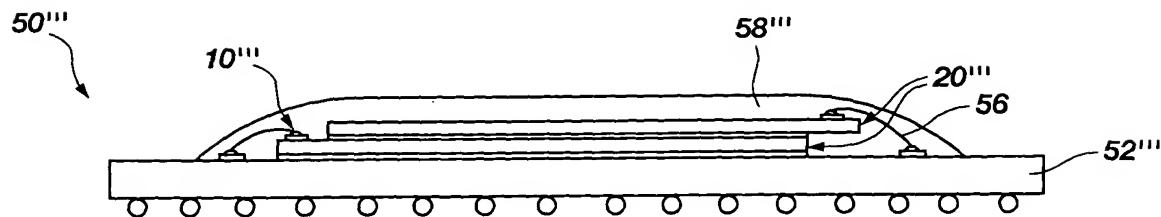
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*Fig. 11*



*Fig. 12*



*Fig. 13*